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Part Number: 0736440206

Status: **Active**

Overview: **HDM Backplane Connector System**

HDM Board-to-Board Backplane Header, Vertical, SMC, Press-Fit, Guide Post Location **Description:**

B, Polarizing Key Position D, 72 Circuits, Mating Length 6.00mm

Documents:

Packaging Specification PK-70873-0818 (PDF) 3D Model

Drawing (PDF) RoHS Certificate of Compliance (PDF)

Agency Certification

CSA LR19980 UL E29179

General

Product Family Backplane Connectors

73644 Series **Application** Backplane

Comments Standard Press-Fit, Standard Press-Fit

Component Type **PCB** Header

Overview **HDM Backplane Connector System**

Product Name HDM

UPC 800754800044

Physical

Circuits (Loaded) 72 Circuits (maximum) 72

Color - Resin Black, Natural

Durability (mating cycles max) 250 First Mate / Last Break No Flammability 94V-0 **Guide to Mating Part** Yes Keying to Mating Part Yes

Material - Metal Phosphor Bronze, Stainless Steel

Material - Plating Mating Gold Material - Plating Termination Gold

Material - Resin High Temperature Thermoplastic

Number of Columns

Number of Pairs Open Pin Field

Number of Rows 6 Orientation Vertical PC Tail Length 3.50mm **PCB** Locator Nο **PCB** Retention Yes PCB Thickness - Recommended 2.50mm Packaging Type Tube Pitch - Mating Interface 2.00mm Pitch - Termination Interface 2.00mm Plating min - Mating 0.762µm Plating min - Termination 0.051µm Polarized to PCB

Surface Mount Compatible (SMC) Yes Temperature Range - Operating -55° to +105°C

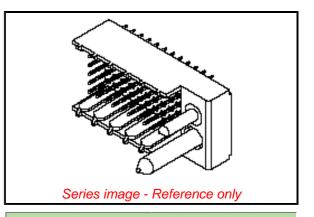
Termination Interface: Style Through Hole - Compliant Pin

No

Yes

Electrical

Stackable



EU ELV

Not Reviewed

China RoHS EU RoHS

Not Reviewed REACH SVHC Not Reviewed **Halogen-Free Status**

Not Reviewed

For more information, please visit Contact US

China ROHS Not Reviewed ELV Not Reviewed RoHS Phthalates Not Reviewed

Search Parts in this Series

73644 Series

Mates With

73632 HDM+ Board-to-Board Daughtercard Receptacle. 73780 HDM Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description Product # Extraction Tool 621001000 Backplane Insertion 621001400

Signal Contact Tool

Backplane Signal 622008502

Insertion Module Press-In Tool for 2.00mm Pitch HDM* Board-to-Board Backplane Header

Current - Maximum per Contact 1.0A 1.0 Gbps Data Rate Real Signals (per 25mm) 75 Shielded No Voltage - Maximum 250V AC

Material Info

Reference - Drawing Numbers Packaging Specification PK-70873-0818 Sales Drawing SDA-73644-XXXX

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